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Ferrites and accessories

EELP 18, EILP 18
Core set (with and without clamp recess)

Series/Type: B66283G, B66283P, B66453G, B66453P, B65804

Date: September 2006



ELP 18/4/10

Core and accessories (with clamp recess)

B66283, B65804

Core set EELP 18

Combination: ELP 18/4/10 with ELP 18/4/10

■ To IEC 62317-9

■ Delivery mode: single units

Magnetic characteristics (per set)

 \odot I/A = 0.62 mm⁻¹

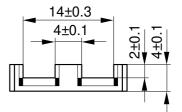
 $I_{a} = 24.3 \text{ mm}$

 $A_{e} = 39.3 \text{ mm}^{2}$

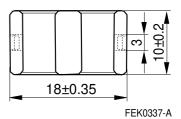
 $A_{min} = 38.9 \text{ mm}^2$

 $V_{\rm p} = 955 \, \rm mm^3$

Approx. weight 4.8 g/set



ELP 18/4/10



Ungapped

Material	A _L value nH	∞e	P _V W/set	Ordering code (per piece)
				. ,
N49	1900 ±25%	930	< 0.25 (50 mT, 500 kHz, 100 °C)	B66283G0000X149
N92	2050 ±25%	1010	< 0.66 (200 mT, 100 kHz, 100 °C)	B66283G0000X192
N87	2600 ±25%	1270	< 0.60 (200 mT, 100 kHz, 100 °C)	B66283G0000X187
N97	2670 ±25%	1314	< 0.47 (200 mT, 100 kHz, 100 °C)	B66283G0000X197

Calculation factors (for formulas, see "E cores: general information") **EELP 18:**

Material	air gap – A _L value		Calculation o	f saturation current			
			K3 (25 °C)	K4 (25 °C)	K3 (100 °C)	K4 (100 °C)	
N87	71.1	-0.773	124	-0.796	104	-0.873	

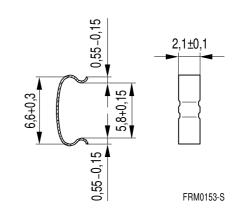
Validity range: K1, K2: 0.10 mm < s < 1.50 mm

K3, K4: $50 \text{ nH} < A_L < 500 \text{ nH}$

Clamp

Ordering code per piece, 2 pieces required

Ordering code: B65804P2204X000





ELP 18/4/10 with I 18/2/10

Core and accessories (with clamp recess)

B66283, B66284

Core set EILP 18
Combination:

ELP 18/4/10 with I 18/2/10

■ To IEC 62317-9

■ Delivery mode: single units

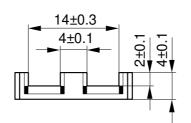
Magnetic characteristics (per set)

© I/A = 0.51 mm⁻¹ $I_e = 20.3 \text{ mm}$

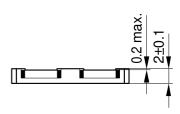
 $A_e = 39.5 \text{ mm}^2$ $A_{min} = 38.9 \text{ mm}^2$

 $V_e = 802 \text{ mm}^3$

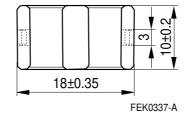
Approx. weight 4.1 g/set

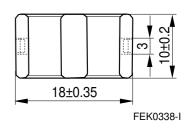


ELP 18/4/10



I 18/2/10





Ungapped

Material	A _L value nH	∞ _e	P _V W/set	Ordering code (per piece)
N49	2100 ±25%	860	< 0.20 (50 mT, 500 kHz, 100 °C)	B66283G0000X149 (ELP core) B66283P0000X149 (I core)
N92	2300 ±25%	930	< 0.55 (200 mT, 100 kHz, 100 °C)	B66283G0000X192 (ELP core) B66283P0000X192 (I core)
N87	2900 ±25%	1180	< 0.50 (200 mT, 100 kHz, 100 °C)	B66283G0000X187 (ELP core) B66283P0000X187 (I core)
N97	3000 ±25%	1230	< 0.40 (200 mT, 100 kHz, 100 °C)	B66283G0000X197 (ELP core) B66283P0000X197 (I core)

Calculation factors (for formulas, see "E cores: general information") **EILP 18:**

Material	air gap – A _L value		Calculation o	of saturation current			
			K3 (25 °C)	K4 (25 °C)	K3 (100 °C)	K4 (100 °C)	
N87	77.4	-0.774	129	-0.796	107	-0.873	

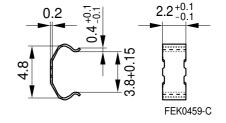
Validity range: K1, K2: 0.10 mm < s < 1.50 mm

K3, K4: $50 \text{ nH} < A_L < 500 \text{ nH}$

Clamp

Ordering code per piece, 2 pieces required

Ordering code: B66284F2204X000





ELP 18/4/10

Core (without clamp recess)

B66453

Core set EELP 18

Combination: ELP 18/4/10 with ELP 18/4/10

■ To IEC 62317-9

■ Delivery mode: single units

Magnetic characteristics (per set)

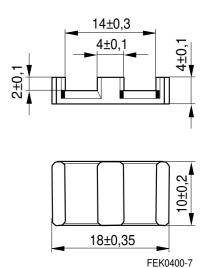
 \odot I/A = 0.62 mm⁻¹

= 24.3 mm

 $A_e = 39.3 \text{ mm}^2$

 $A_{min} = 38.9 \text{ mm}^2$ $V_e = 955 \text{ mm}^3$

Approx. weight 4.8 g/set



ELP 18/4/10

Ungapped

Material	A _L value nH	∞ _e	P _V W/set	Ordering code (per piece)
N49	1900 ±25%	930	< 0.25 (50 mT, 500 kHz, 100 °C)	B66453G0000X149
N92	2050 ±25%	1010	< 0.66 (200 mT, 100 kHz, 100 °C)	B66453G0000X192
N87	2600 ±25%	1270	< 0.60 (200 mT, 100 kHz, 100 °C)	B66453G0000X187
N97	2650 ±25%	1300	< 0.50 (200 mT, 100 kHz, 100 °C)	B66453G0000X197

Calculation factors (for formulas, see "E cores: general information") **EELP 18:**

Material	Relationship between air gap – A _L value		Calculation o	f saturation cu	rrent		
	K1 (25 °C)	K2 (25 °C)	K3 (25 °C)	K4 (25 °C)	K3 (100 °C)	K4 (100 °C)	
N87	71.1	-0.773	124	-0.796	104	-0.873	

Validity range: K1, K2: 0.10 mm < s < 1.50 mm

K3, K4: $50 \text{ nH} < A_L < 500 \text{ nH}$



ELP 18/4/10 with I 18/2/10

Core (without clamp recess)

B66453

Core set EILP 18
Combination:

ELP 18/4/10 with I 18/2/10

■ To IEC 62317-9

■ Delivery mode: single units

Magnetic characteristics (per set)

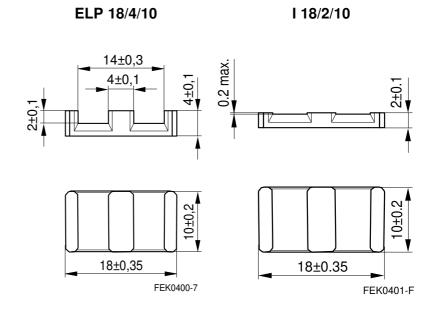
 $l_e = 20.3 \text{ mm}$

 $A_e = 39.5 \text{ mm}^2$

 $A_{min} = 38.9 \text{ mm}^2$

 $V_e = 802 \text{ mm}^3$

Approx. weight 4.1 g/set



Ungapped

Material	A _L value nH	∞e	P _V W/set	Ordering code (per piece)
N49	2100 ±25%	860	< 0.20 (50 mT, 500 kHz, 100 °C)	B66453G0000X149 (ELP core) B66453P0000X149 (I core)
N92	2300 ±25%	930	< 0.55 (200 mT, 100 kHz, 100 °C)	B66453G0000X192 (ELP core) B66453P0000X192 (I core)
N87	2900 ±25%	1180	< 0.50 (200 mT, 100 kHz, 100 °C)	B66453G0000X187 (ELP core) B66453P0000X187 (I core)
N97	3000 ±25%	1227	< 0.42 (200 mT, 100 kHz, 100 °C)	B66453G0000X197 (ELP core) B66453P0000X197 (I core)

Calculation factors (for formulas, see "E cores: general information") **EILP 18:**

Material	Relationship between air gap – A _L value		Calculation o	f saturation cu			
	K1 (25 °C)	K2 (25 °C)	K3 (25 °C)	K4 (25 °C)	K3 (100 °C)	K4 (100 °C)	
N87	77.4	-0.774	129	-0.796	107	-0.873	

Validity range: K1, K2: 0.10 mm < s < 1.50 mm

K3, K4: $50 \text{ nH} < A_L < 500 \text{ nH}$



Ferrites and accessories

Cautions and warnings

Mechanical stress and mounting

Ferrite cores have to meet mechanical requirements during assembling and for a growing number of applications. Since ferrites are ceramic materials one has to be aware of the special behavior under mechanical load.

As valid for any ceramic material, ferrite cores are brittle and sensitive to any shock, fast changing or tensile load. Especially high cooling rates under ultrasonic cleaning and high static or cyclic loads can cause cracks or failure of the ferrite cores.

For detailed information see Data Book 2007, chapter "General - Definitions, 8.1".

Effects of core combination on A_I value

Stresses in the core affect not only the mechanical but also the magnetic properties. It is apparent that the initial permeability is dependent on the stress state of the core. The higher the stresses are in the core, the lower is the value for the initial permeability. Thus the embedding medium should have the greatest possible elasticity.

For detailed information see Data Book 2007, chapter "General – Definitions, 8.2".

Heating up

Ferrites can run hot during operation at higher flux densities and higher frequencies.

NiZn-materials

The magnetic properties of NiZn-materials can change irreversible in high magnetic fields.

Processing notes

- The start of the winding process should be soft. Else the flanges may be destroid.
- To strong winding forces may blast the flanges or squeeze the tube that the cores can no more be mount.
- To long soldering time at high temperature (>300 °C) may effect coplanarity or pin arrangement.
- Not following the processing notes for soldering of the J-leg terminals may cause solderability problems at the transformer because of pollution with Sn oxyd of the tin bath or burned insulation of the wire. For detailed information see Data Book 2007, chapter "Processing notes, 2.2".
- The dimensions of the hole arrangement have fixed values and should be understood as a recommendation for drilling the printed circuit board. For dimensioning the pins, the group of holes can only be seen under certain conditions, as they fit into the given hole arrangement. To avoid problems when mounting the transformer, the manufacturing tolerances for positioning the customers' drilling process must be considered by increasing the hole diameter.



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